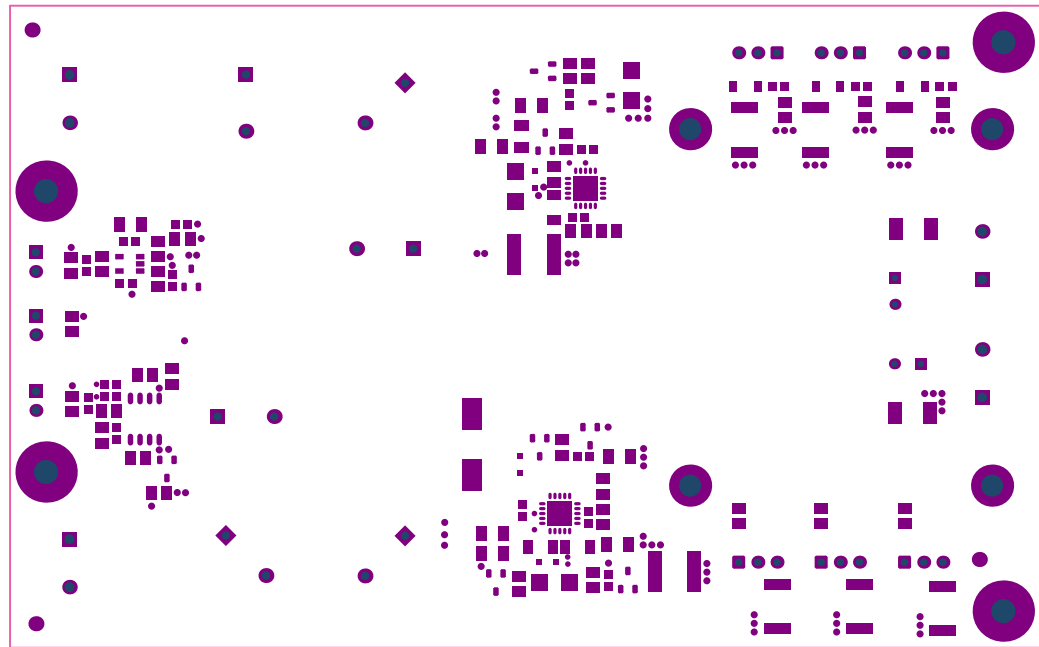


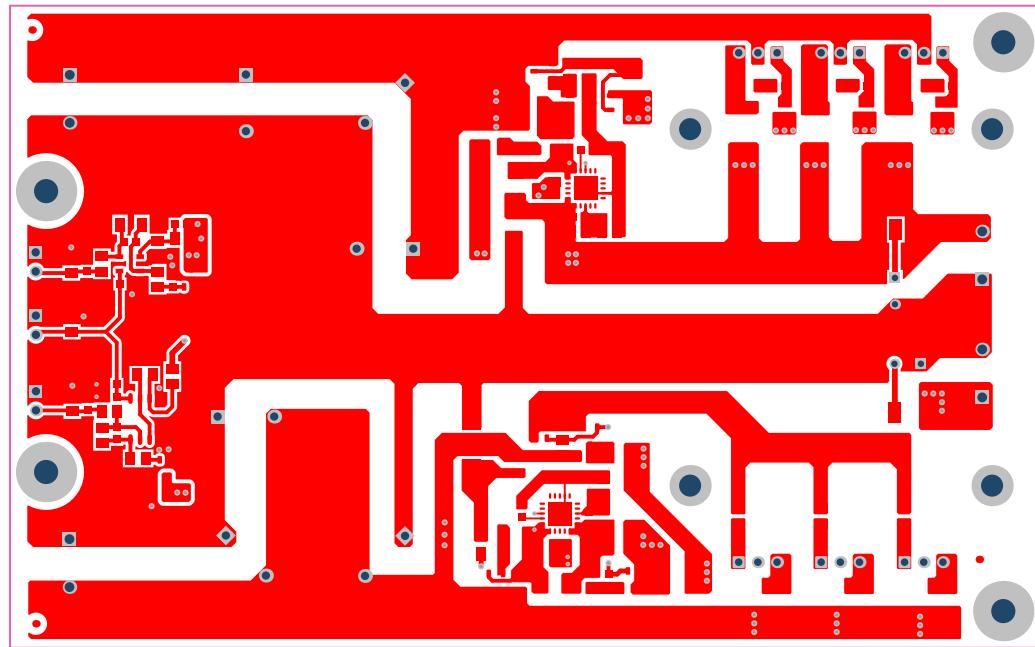
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01371	REV: E2	SUN REV: Not In VersionControl
LAYER NAME = Top Overlay	TID #: TIDA-01371		
PLOT NAME = Top Overlay	GENERATED : 12/8/2016 5:31:16 PM		TEXAS INSTRUMENTS



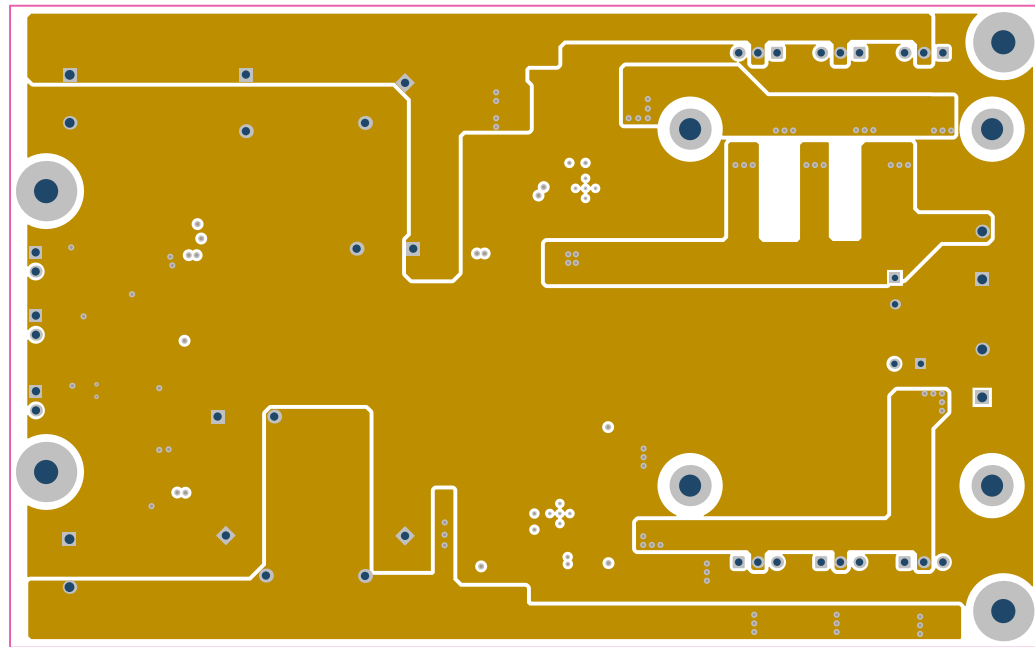
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01371	REV: E2	SUN REV: Not In VersionControl
LAYER NAME = Top Paste	TID #: TIDA-01371		
PLOT NAME = Top Paste	GENERATED : 12/8/2016 5:31:17 PM	TEXAS INSTRUMENTS	



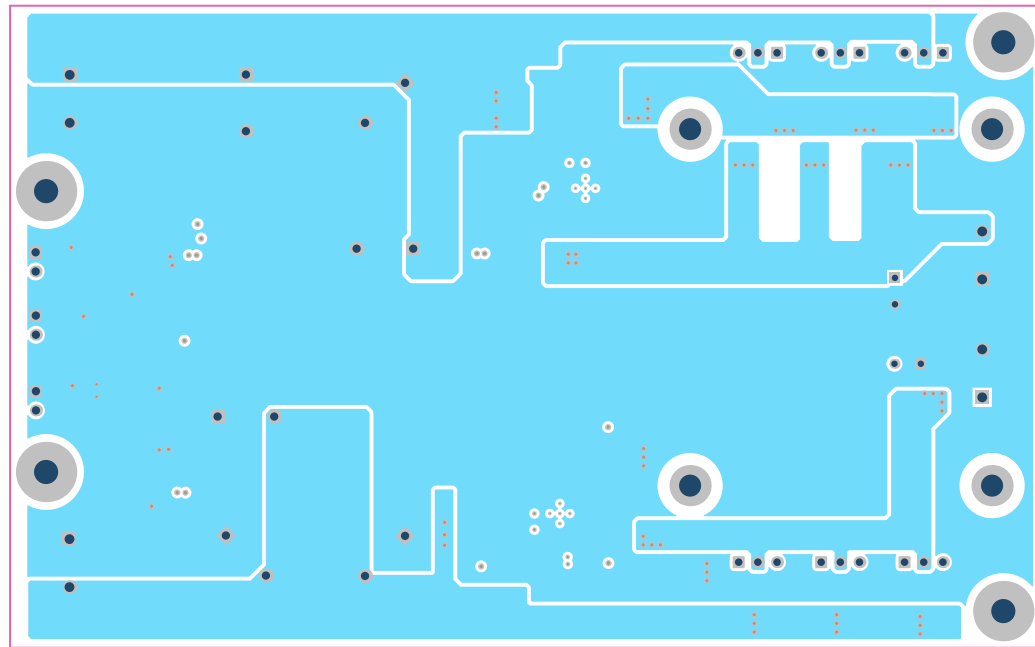
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01371	REV: E2	SUN REV: Not In VersionControl
LAYER NAME = Top Solder	TID #: TIDA-01371		
PLOT NAME = Top Solder Mask	GENERATED : 12/8/2016 5:31:18 PM	TEXAS INSTRUMENTS	



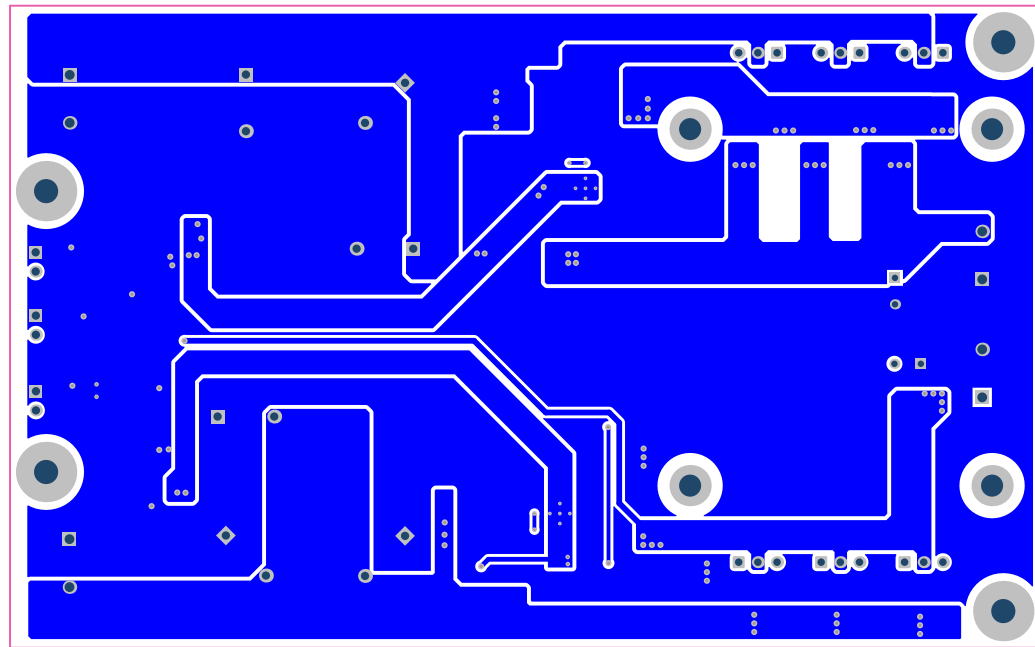
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01371	REV: E2	SUN REV: Not In VersionControl
LAYER NAME = Top Layer	TID #: TIDA-01371		
PLOT NAME = Top Layer	GENERATED : 12/8/2016 5:31:19 PM	TEXAS INSTRUMENTS	



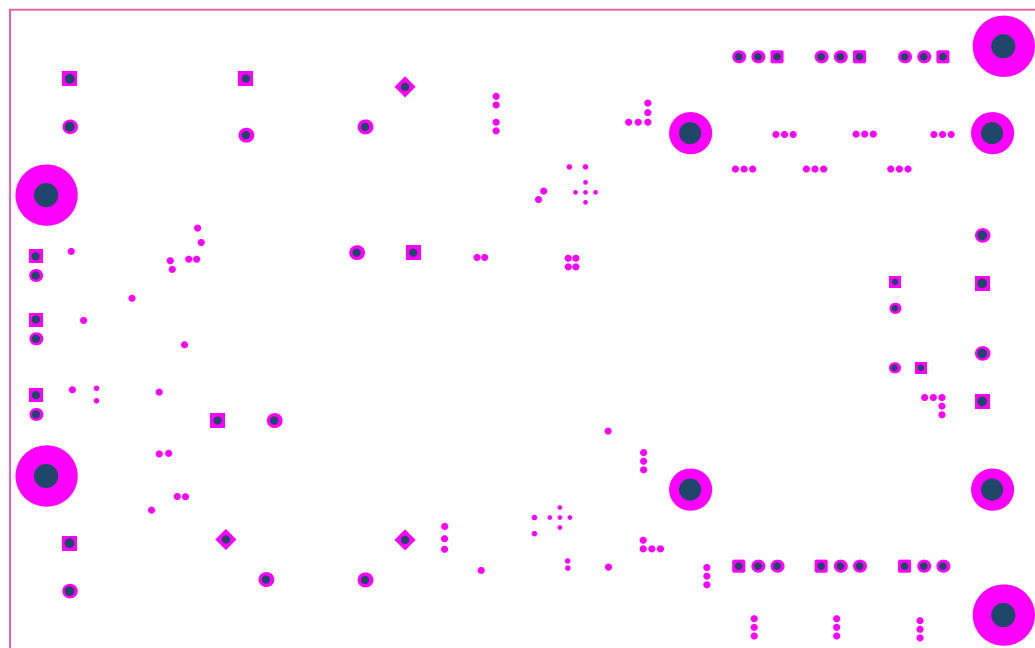
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01371	REV: E2	SUN REV: Not In VersionControl
LAYER NAME = GND Layer	TID #: TIDA-01371		
PLOT NAME = GND	GENERATED : 12/8/2016 5:31:20 PM	TEXAS INSTRUMENTS	



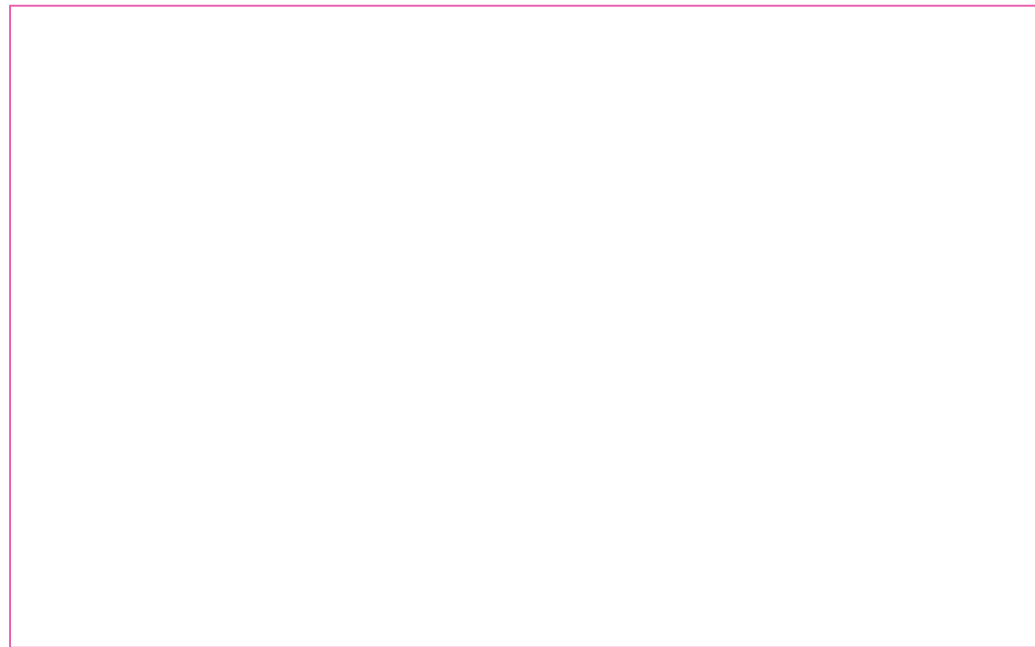
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01371	REV: E2	SUN REV: Not In VersionControl
LAYER NAME = PWR Layer	TID #: TIDA-01371		
PLOT NAME = PWR	GENERATED : 12/8/2016 5:31:21 PM	TEXAS INSTRUMENTS	



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01371	REV: E2	SUN REV: Not In VersionControl
LAYER NAME = Bottom Layer	TID #: TIDA-01371		
PLOT NAME = Bottom Layer	GENERATED : 12/8/2016 5:31:21 PM	TEXAS INSTRUMENTS	



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01371	REV: E2	SUN REV: Not In VersionControl
LAYER NAME = Bottom Solder	TID #: TIDA-01371		
PLOT NAME = Bottom Solder Mask	GENERATED : 12/8/2016	5:31:22 PM	TEXAS INSTRUMENTS



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01371	REV: E2	SUN REV: Not In VersionControl
LAYER NAME = Bottom Overlay	TID #: TIDA-01371		
PLOT NAME = Bottom Overlay	GENERATED : 12/8/2016 5:31:23 PM	TEXAS INSTRUMENTS	



Symbol	Count	Hole Size	Plated	Hole Type
⊗	4	33.46mil (0.850mm)	PTH	Round
⊛	4	115.00mil (2.921mm)	PTH	Round
○	4	125.98mil (3.200mm)	PTH	Round
▽	8	12.00mil (0.305mm)	PTH	Round
▲	8	51.18mil (1.300mm)	PTH	Round
E	10	7.87mil (0.200mm)	PTH	Round
C	18	39.37mil (1.000mm)	PTH	Round
D	18	43.31mil (1.100mm)	PTH	Round
□	82	16.00mil (0.406mm)	PTH	Round
	156 Total			

DRILL TOLERANCE
 FOR PTH +/- 3MIL
 7.874mil drills+0/-7.874mil
 12mil drills+0/-12mil
 16mil drills+0/-16mil

Layer Name	Server Document	Copper Thickness	Dielectric Material
Top Solder Mask	(.GTS)		Solder Resist
Top Layer	(.GTL)	1.4mil	FR4-High Tg
GNL	(.G1)	1.4mil	FR4-High Tg
DLR	(.G2)	1.4mil	FR4-High Tg
Bottom Layer	(.GBL)	1.4mil	FR4-High Tg
Bottom Solder Mask	(.GBS)		Solder Resist

DESIGN INFORMATION

BOARD SIZE (REFER ALSO ARRAY/PANEL PROFILING INFORMATION)
 137 mm X 85 mm

Number of Layers: 4
 MIN. TRACK WIDTH: 10 MIL
 MIN. CLEARANCE: 8.59 MIL
 MIN. VIA PAD SIZE: 19.695 MIL

MINIMUM ANNULAR RING: 5.9055 MIL EXTERNAL
 PER IPC-D-275 CLASS 2 LEVEL C
 REGISTRATION TOLERANCES: METAL +/- 5 MIL HOLES +/- 3 MIL

MATERIAL:
 FR-408 FR-4 High Tg OTHER _____
 THICKNESS: 63 MIL (1.6mm) +/-10% OTHER _____
 TOLERANCE: ANSI IPC-6012 TYPE 3 CLASS 2
 OTHER +/- _____
 BOW & TWIST: ANSI IPC-6012 TYPE 3 CLASS 2
 OTHER +/- _____

COPPER THICKNESS (FINISHED):
 OUTER: 1.4MIL (1oz) 2MIL (1.4oz) 2.8MIL (2oz)
 INNER SIGNAL: 1.4MIL (1oz) 2.8MIL (2oz) N/A

DRILLING:
 REFERENCE: AS SHOWN NO_DRILL_FILES
 PTH MIN COPPER THICKNESS: 1MIL OTHER _____

BOARD FINISH:
 SILKSCREEN: TOP BOTTOM
 SILKSCREEN COLOR: WHITE OTHER _____
 SOLDER RESIST COLOR: GREEN BLUE OTHER _____

SURFACE FINISH: IMMERSION GOLD (ENG) ENERP
 MM. TN/SILVER OR EQUIV OTHER _____

ARRAY/PANEL: CUT AND TRIM PER MECH LAYER 1
 N.C. ROUTE V. SCORE

CERTIFICATION: MATERIALS AND WORKMANSHIP FOR ALL PCBs TO MEET OR EXCEED THE REQUIREMENTS OF:
 ANSI IPC-A-600F CLASS -> 1 2 3
 UL 94V-0 RoHS OTHER PER ORDER

ADDITIONAL REQUIREMENTS: VIA TEXTING: YES NO IMPEDANCE CONTROL: YES NO
 MICROSECTION: YES BARE BOARD ELEC. TEST: NONE REQUIRED PER ORDER

MANUFACTURERS UL: RAL METAL SILK



PROJECT TITLE:
 Floating Tracking Programmable Regulator

DESIGNED FOR:
 Public Release

FILE NAME:
 TIDA-01371-E2.PcbDoc

ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01371	REV: E2	SUN REV: Not In VersionControl
LAYER NAME = Drill Drawing	TID #: TIDA-01371		
PLOT NAME = Drill Drawing	GENERATED : 12/8/2016 5:31:25 PM	TEXAS INSTRUMENTS	

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ENGINEER: Sanjay Pithadia	LAYOUT BY: Avinash N
SCALE: 1.00	ALTIUM DESIGNER VERSION: 16.1.9.221



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01371	REV: E2	SUN REV: Not In VersionControl
LAYER NAME = M1 Board Outline	TID #: TIDA-01371		
PLOT NAME = Board Dimensions	GENERATED : 12/8/2016	5:31:26 PM	TEXAS INSTRUMENTS

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